

3.3V 4M x 4-Bit EDO-Dynamic RAM

HYB3116405BJ/BT(L) -50/-60/-70

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Advanced Information

- 4 194 304 words by 4-bit organization
- 0 to 70 °C operating temperature
- Performance

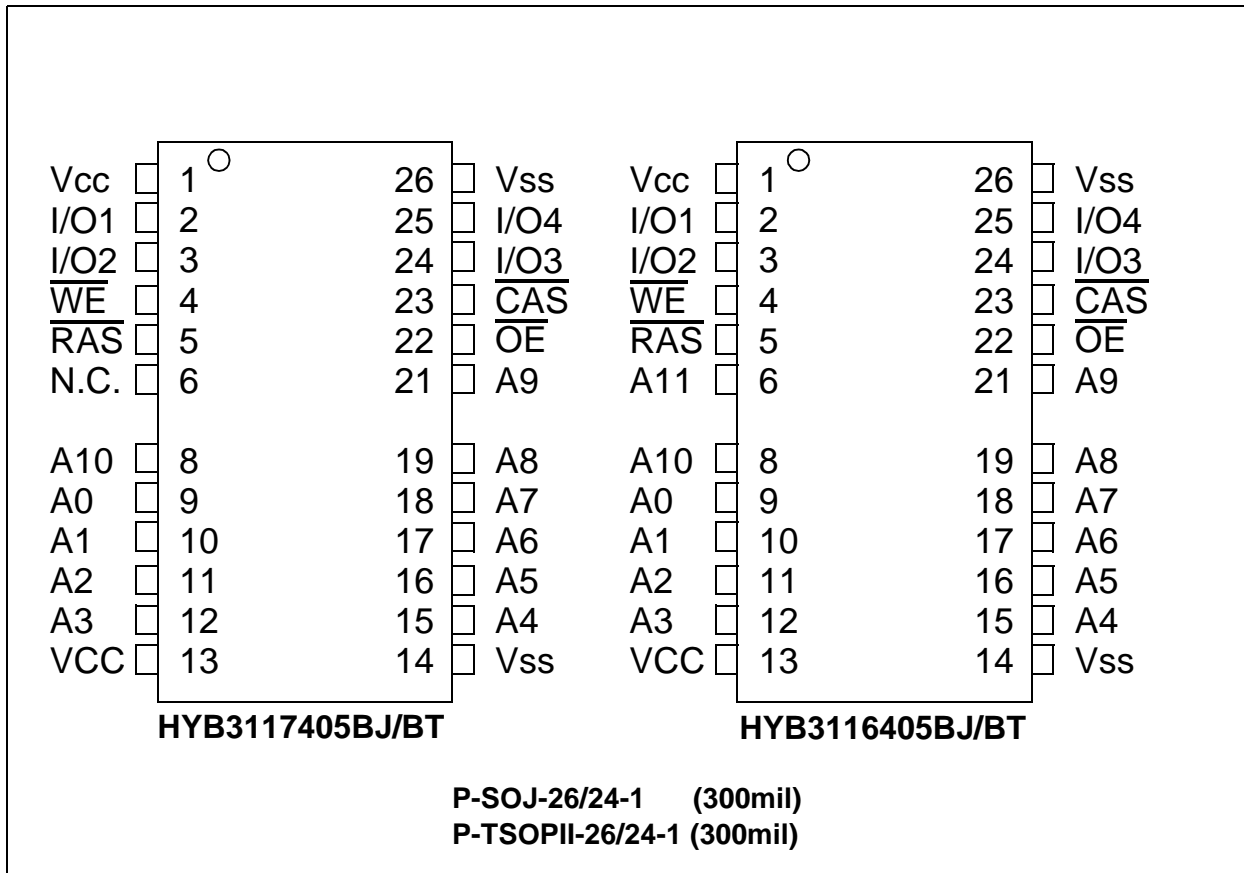
		-50	-60	-70	
t _{RAC}	$\overline{\text{RAS}}$ access time	50	60	70	ns
t _{CAC}	$\overline{\text{CAS}}$ access time	13	15	20	ns
t _{AA}	Access time from address	25	30	35	ns
t _{RC}	Read/Write cycle time	84	104	124	ns
t _{HPC}	Hyper page mode (EDO) cycle time	20	25	30	ns

- Single + 3.3 V (± 0.3V) supply
- Low power dissipation
 - max. 396 active mW (HYB3117405BJ/BT-50)
 - max. 363 active mW (HYB3117405BJ/BT-60)
 - max. 330 active mW (HYB3117405BJ/BT-70)
 - max. 360 active mW (HYB3116405BJ/BT-50)
 - max. 324 active mW (HYB3116405BJ/BT-60)
 - max. 288 active mW (HYB3116405BJ/BT-70)
 - 7.2 mW standby (LV-TTL)
 - 3.6 mW standby (LV-CMOS)
 - 720 µW standby for L-version
- Output unlatched at cycle end allows two-dimensional chip selection
- Read, write, read-modify-write, $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh, $\overline{\text{RAS}}$ -only refresh, hidden refresh, Self Refresh and test mode
- Hyper page mode (EDO) capability
- All inputs, outputs and clocks fully TTL-compatible
- 2048 refresh cycles / 32 ms for HYB3117405
- 4096 refresh cycles / 64 ms for HYB3116405
- Plastic Package:
 - P-SOJ-26/24-1 (300 mil)
 - P-TSOPII-26/24-1 (300mil)

The HYB 3116(7)405BJ/BT(L) is a 16MBit dynamic RAM organized as 4194304 words by 4-bits. The HYB 3116(7)405BJ/BT(L) utilizes a submicron CMOS silicon gate process technology, as well as advanced circuit techniques to provide wide operating margins, both internally and for the system user. Multiplexed address inputs permit the HYB 3116(7)405BJ/BT(L) to be packaged in a standard SOJ 26/24 300 mil or TSOPII-26/24 300 mil wide plastic package. These packages provide high system bit densities and are compatible with commonly used automatic testing and insertion equipment. System-oriented features include single + 3.3 V (± 0.3 V) power supply, direct interfacing with high-performance logic device families. The HYB3116405BTL parts have a very low power „sleep mode“ supported by Self Refresh.

Ordering Information

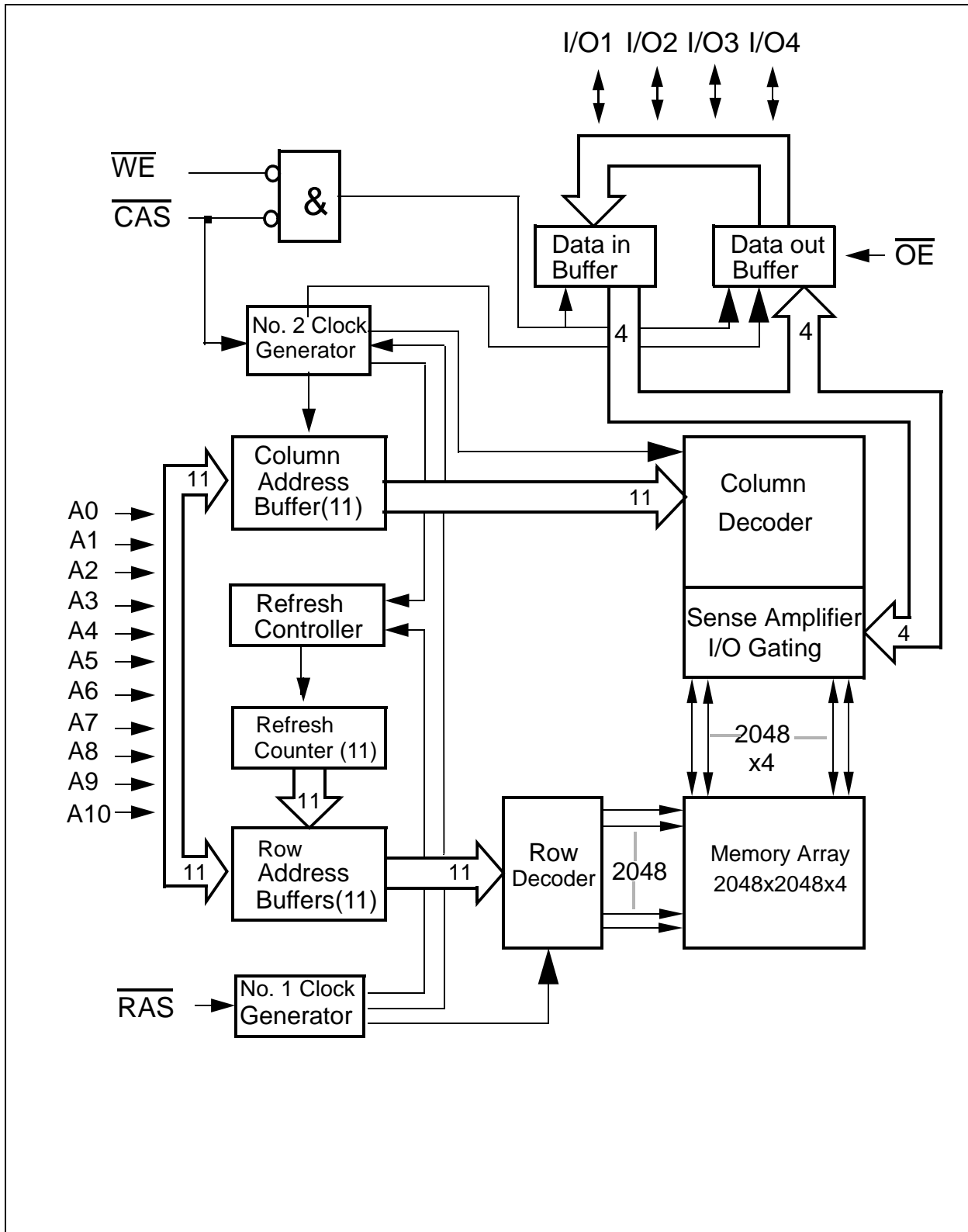
Type	Ordering Code	Package	Descriptions
HYB 3117405BJ-50	Q67100-Q1119	P-SOJ-26/24-1 300 mil	DRAM (access time 50 ns)
HYB 3117405BJ-60	Q67100-Q1120	P-SOJ-26/24-1 300 mil	DRAM (access time 60 ns)
HYB 3117405BJ-70		P-SOJ-26/24-1 300 mil	DRAM (access time 70 ns)
HYB 3117405BT-50	Q67100-Q1135	P-TSOPII-26/24-1 300 mil	DRAM (access time 50 ns)
HYB 3117405BT-60	Q67100-Q1136	P-TSOPII-26/24-1 300 mil	DRAM (access time 60 ns)
HYB 3117405BT-70	Q67100-Q1184	P-TSOPII-26/24-1 300 mil	DRAM (access time 70 ns)
HYB 3116405BJ-50	Q67100-Q1127	P-SOJ-26/24-1 300 mil	DRAM (access time 50 ns)
HYB 3116405BJ-60	Q67100-Q1128	P-SOJ-26/24-1 300 mil	DRAM (access time 60 ns)
HYB 3116405BJ-70		P-SOJ-26/24-1 300 mil	DRAM (access time 70 ns)
HYB 3116405BT-50	Q67100-Q1143	P-TSOPII-26/24-1 300 mil	DRAM (access time 50 ns)
HYB 3116405BT-60	Q67100-Q1144	P-TSOPII-26/24-1 300 mil	DRAM (access time 60 ns)
HYB 3116405BT-70	Q67100-Q1186	P-TSOPII-26/24-1 300 mil	DRAM (access time 70 ns)
HYB 3116405BTL-50	on request	P-TSOPII-26/24-1 300 mil	LP-DRAM (access time 50 ns)
HYB 3116405BTL-60	on request	P-TSOPII-26/24-1 300 mil	LP-DRAM (access time 60 ns)
HYB 3116405BTL-70	on request	P-TSOPII-26/24-1 300 mil	LP-DRAM (access time 70 ns)



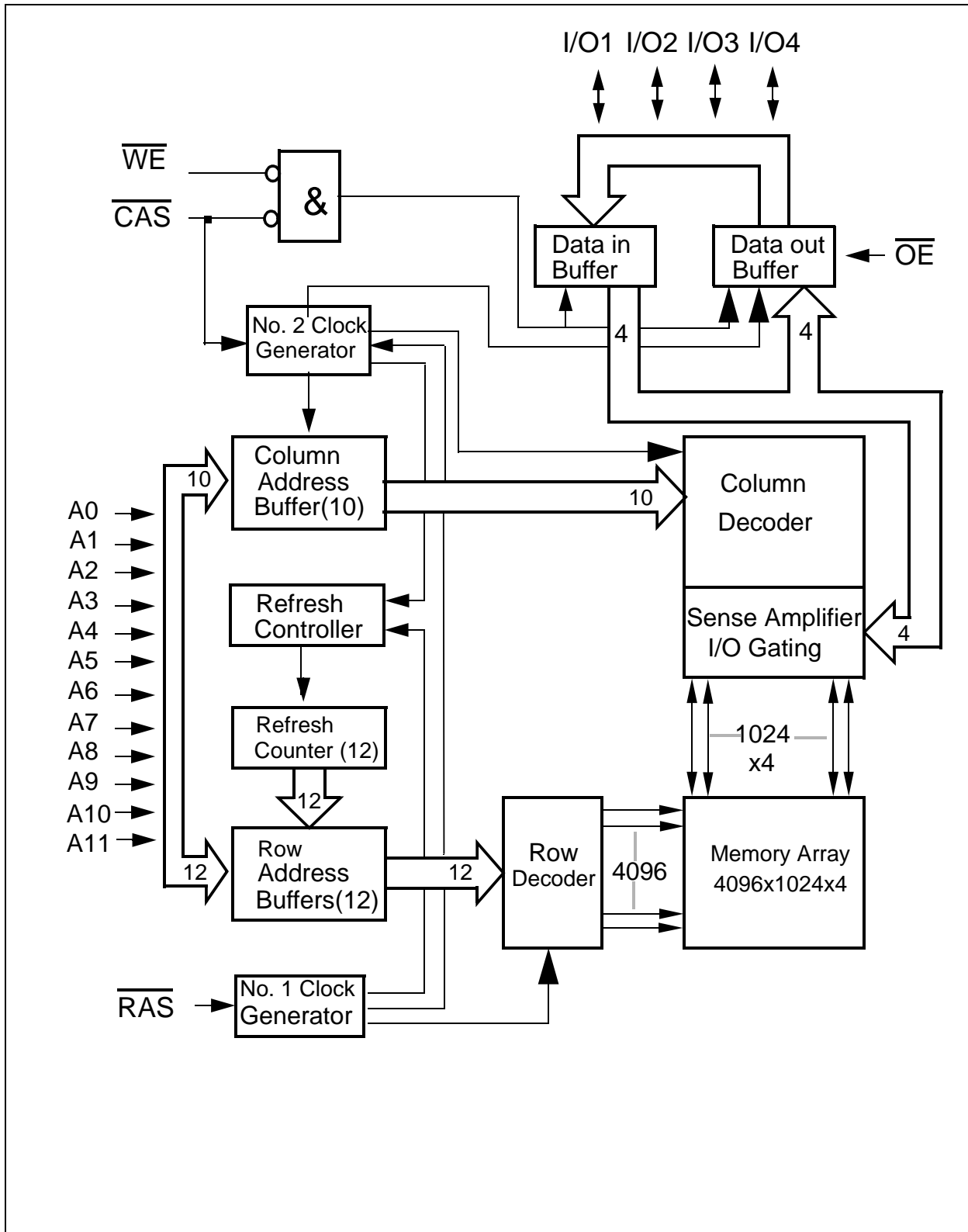
Pin Configuration

Pin Names

A0 to A10	Row & Column Address Inputs for HYB3117405
A0 to A11	Row Address Inputs for HYB3116405
A0 to A9	Column Address Inputs for HYB3116405
$\overline{\text{RAS}}$	Row Address Strobe
$\overline{\text{OE}}$	Output Enable
I/O1 -I/O4	Data Input/Output
$\overline{\text{CAS}}$	Column Address Strobe
$\overline{\text{WE}}$	Read/Write Input
V _{cc}	Power Supply (+ 3.3 V)
V _{ss}	Ground (0 V)
N.C.	not connected



Block Diagram for HYB3117405



Block Diagram for HYB3116405

Absolute Maximum Ratings

Operating temperature range	0 to 70 °C
Storage temperature range.....	- 55 to 150 °C
Input/output voltage	-0.5 to min($V_{CC}+0.5$, 4.6) V
Power supply voltage.....	- 0.5 V to 4.6 V
Power dissipation.....	0.5 W
Data out current (short circuit)	50 mA

Note:

Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage of the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics (values in brackets for HYB3117405)

$T_A = 0$ to 70 °C, $V_{SS} = 0$ V, $V_{CC} = 3.3$ V \pm 0.3 V, $t_T = 2$ ns

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Input high voltage	V_{IH}	2.0	$V_{CC}+0.5$	V	1)
Input low voltage	V_{IL}	- 0.5	0.8	V	1)
TTL Output high voltage ($I_{OUT} = - 2$ mA)	V_{OH}	2.4	-	V	1)
TTL Output low voltage ($I_{OUT} = 2$ mA)	V_{OL}	-	0.4	V	1)
CMOS Output high voltage ($I_{OUT} = -100$ uA)	V_{OH}	$V_{CC}-0.2$	-	V	
CMOS Output low voltage ($I_{OUT} = 100$ uA)	V_{OL}	-	0.2	V	
Input leakage current (0 V $\leq V_{IH} \leq V_{CC} + 0.3$ V, all other pins = 0 V)	$I_{I(L)}$	- 10	10	μ A	1)
Output leakage current (DO is disabled, 0 V $\leq V_{OUT} \leq V_{CC} + 0.3$ V)	$I_{O(L)}$	- 10	10	μ A	1)
Average V_{CC} supply current: -50 ns version -60 ns version -70 ns version	I_{CC1}	-	100(120) 90 (110) 80 (100)	mA mA mA	2) 3) 4) 2) 3) 4) 2) 3) 4)
(\overline{RAS} , \overline{CAS} , address cycling, $t_{RC} = t_{RC}$ min.)					
Standby V_{CC} supply current ($\overline{RAS} = \overline{CAS} = V_{IH}$)	I_{CC2}	-	2	mA	-

DC Characteristics (values in brackets for HYB3117405)

$T_A = 0$ to 70 °C, $V_{SS} = 0$ V, $V_{CC} = 3.3$ V \pm 0.3 V, $t_T = 2$ ns

Parameter	Symbol	Limit Values		Unit	Test Condition
		min.	max.		
Average V_{CC} supply current, during \overline{RAS} -only refresh cycles: -50 ns version -60 ns version -70 ns version	I_{CC3}	–	100(120)	mA	2) 4)
		–	90 (110)	mA	2) 4)
		–	80 (100)	mA	2) 4)
(\overline{RAS} cycling: $\overline{CAS} = V_{IH}$, $t_{RC} = t_{RC}$ min.)					
Average V_{CC} supply current, during hyper page mode EDO): -50 ns version -60 ns version -70 ns version	I_{CC4}	–	70 (70)	mA	2) 3) 4)
		–	55 (55)	mA	2) 3) 4)
		–	45 (45)	mA	2) 3) 4)
($\overline{RAS} = V_{IL}$, \overline{CAS} , address cycling, $t_{PC} = t_{PC}$ min.)					
Standby V_{CC} supply current ($\overline{RAS} = \overline{CAS} = V_{CC} - 0.2$ V)	I_{CC5}	–	1 200	mA μ A	1) L-version
Average V_{CC} supply current, during \overline{CAS} -before-RAS refresh mode: -50 ns version -60 ns version -70 ns version	I_{CC6}	–	100(120)	mA	2) 4)
		–	90 (110)	mA	2) 4)
		–	80 (100)	mA	2) 4)
(\overline{RAS} , \overline{CAS} cycling, $t_{RC} = t_{RC}$ min.)					
Average Self Refresh Current (CBR cycle with $t_{RAS} > t_{RASmin.}$, \overline{CAS} held low, $\overline{WE} = V_{CC} - 0.2$ V, Address and Din = $V_{CC} - 0.2$ V or 0.2V)	I_{CC7}	–	1 250	mA μ A	L-version

Capacitance

$T_A = 0$ to 70 °C, $V_{CC} = 3.3$ V \pm 0.3V, $f = 1$ MHz

Parameter	Symbol	Limit Values		Unit
		min.	max.	
Input capacitance (A0 to A10, A11)	C_{I1}	–	5	pF
Input capacitance (\overline{RAS} , \overline{CAS} , \overline{WE} , \overline{OE})	C_{I2}	–	7	pF
I/O capacitance (I/O1 - I/O4)	C_{I0}	–	7	pF

AC Characteristics ⁵⁾⁶⁾

16E

$T_A = 0$ to 70 °C, $V_{CC} = 5$ V \pm 10 %, $t_T = 2$ ns

Parameter	Symbol	Limit Values						Unit	Note
		-50		-60		-70			
		min.	max.	min.	max.	min.	max.		

common parameters

Random read or write cycle time	t_{RC}	84	–	104	–	124	–	ns	
\overline{RAS} precharge time	t_{RP}	30	–	40	–	50	–	ns	
\overline{RAS} pulse width	t_{RAS}	50	10k	60	10k	70	10k	ns	
\overline{CAS} pulse width	t_{CAS}	8	10k	10	10k	12	10k	ns	
Row address setup time	t_{ASR}	0	–	0	–	0	–	ns	
Row address hold time	t_{RAH}	8	–	10	–	10	–	ns	
Column address setup time	t_{ASC}	0	–	0	–	0	–	ns	
Column address hold time	t_{CAH}	8	–	10	–	12	–	ns	
\overline{RAS} to \overline{CAS} delay time	t_{RCD}	12	37	14	45	14	53	ns	
\overline{RAS} to column address delay	t_{RAD}	10	25	12	30	12	35	ns	
\overline{RAS} hold time	t_{RSH}	13		15	–	17	–	ns	
\overline{CAS} hold time	t_{CSH}	40		50	–	60	–	ns	
\overline{CAS} to \overline{RAS} precharge time	t_{CRP}	5	–	5	–	5	–	ns	
Transition time (rise and fall)	t_T	1	50	1	50	1	50	ns	7
Refresh period for HYB5116405	t_{REF}	–	64	–	64	–	64	ms	
Refresh period for HYB5117405	t_{REF}	–	32	–	32	–	32	ms	
Refresh period for L-version	t_{REF}	–	256	–	256	–	256	ms	

Read Cycle

Access time from \overline{RAS}	t_{RAC}	–	50	–	60	–	70	ns	8, 9
Access time from \overline{CAS}	t_{CAC}	–	13	–	15	–	17	ns	8, 9
Access time from column address	t_{AA}	–	25	–	30	–	35	ns	8,10
\overline{OE} access time	t_{OEA}	–	13	–	15	–	17	ns	
Column address to \overline{RAS} lead time	t_{RAL}	25	–	30	–	35	–	ns	
Read command setup time	t_{RCS}	0	–	0	–	0	–	ns	
Read command hold time	t_{RCH}	0	–	0	–	0	–	ns	11
Read command hold time referenced to \overline{RAS}	t_{RRH}	0	–	0	–	0	–	ns	11
\overline{CAS} to output in low-Z	t_{CLZ}	0	–	0	–	0	–	ns	8

AC Characteristics (cont'd) 5)6)

16E

 $T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}, V_{CC} = 5 \text{ V} \pm 10 \%, t_T = 2 \text{ ns}$

Parameter	Symbol	Limit Values						Unit	Note
		-50		-60		-70			
		min.	max.	min.	max.	min.	max.		
Output buffer turn-off delay	t_{OFF}	0	13	0	15	0	17	ns	12
Output turn-off delay from \overline{OE}	t_{OEZ}	0	13	0	15	0	17	ns	12
Data to \overline{CAS} low delay	t_{DZC}	0	–	0	–	0	–	ns	13
Data to \overline{OE} low delay	t_{DZO}	0	–	0	–	0	–	ns	13
\overline{CAS} high to data delay	t_{CDD}	10	–	13	–	15	–	ns	14
\overline{OE} high to data delay	t_{ODD}	10	–	13	–	15	–	ns	14

Write Cycle

Write command hold time	t_{WCH}	8	–	10	–	10	–	ns	
Write command pulse width	t_{WCP}	8	–	10	–	10	–	ns	
Write command setup time	t_{WCS}	0	–	0	–	0	–	ns	15
Write command to \overline{RAS} lead time	t_{RWL}	13	–	15	–	17	–	ns	
Write command to \overline{CAS} lead time	t_{CWL}	13	–	15	–	17	–	ns	
Data setup time	t_{DS}	0	–	0	–	0	–	ns	16
Data hold time	t_{DH}	8	–	10	–	12	–	ns	16

Read-modify-Write Cycle

Read-write cycle time	t_{RWC}	113	–	138	–	162	–	ns	
\overline{RAS} to \overline{WE} delay time	t_{RWD}	64	–	77	–	89	–	ns	15
\overline{CAS} to \overline{WE} delay time	t_{CWD}	27	–	32	–	36	–	ns	15
Column address to \overline{WE} delay time	t_{AWD}	39	–	47	–	54	–	ns	15
\overline{OE} command hold time	t_{OEH}	10	–	13	–	15	–	ns	

Hyper Page Mode (EDO) Cycle

Hyper page mode (EDO) cycle time	t_{HPC}	20	–	25	–	30	–	ns	
\overline{CAS} precharge time	t_{CP}	8	–	10	–	10	–	ns	
Access time from \overline{CAS} precharge	t_{CPA}	–	27	–	32	–	37	ns	7
Output data hold time	t_{COH}	5	–	5	–	5	–	ns	
\overline{RAS} pulse width in EDO mode	t_{RAS}	50	200k	60	200k	70	200k	ns	

AC Characteristics (cont'd) 5)6)

16E

 $T_A = 0 \text{ to } 70 \text{ }^\circ\text{C}, V_{CC} = 5 \text{ V} \pm 10 \%, t_T = 2 \text{ ns}$

Parameter	Symbol	Limit Values						Unit	Note
		-50		-60		-70			
		min.	max.	min.	max.	min.	max.		
$\overline{\text{CAS}}$ precharge to $\overline{\text{RAS}}$ Delay	t_{RHPC}	27	–	32	–	37	–	ns	

Hyper Page Mode (EDO) Read-modify-Write Cycle

Hyper page mode (EDO) read-write cycle time	t_{PRWC}	58	–	68	–	77	–	ns	
$\overline{\text{CAS}}$ precharge to $\overline{\text{WE}}$	t_{CPWD}	41	–	49	–	56	–	ns	

$\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Refresh Cycle

$\overline{\text{CAS}}$ setup time	t_{CSR}	10	–	10	–	10	–	ns	
$\overline{\text{CAS}}$ hold time	t_{CHR}	10	–	10	–	10	–	ns	
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ precharge time	t_{RPC}	5	–	5	–	5	–	ns	
Write to $\overline{\text{RAS}}$ precharge time	t_{WRP}	10	–	10	–	10	–	ns	
Write hold time referenced to $\overline{\text{RAS}}$	t_{WRH}	10	–	10	–	10	–	ns	

$\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ Counter Test Cycle

$\overline{\text{CAS}}$ precharge time	t_{CPT}	35	–	40	–	40	–	ns	
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Self Refresh Cycle

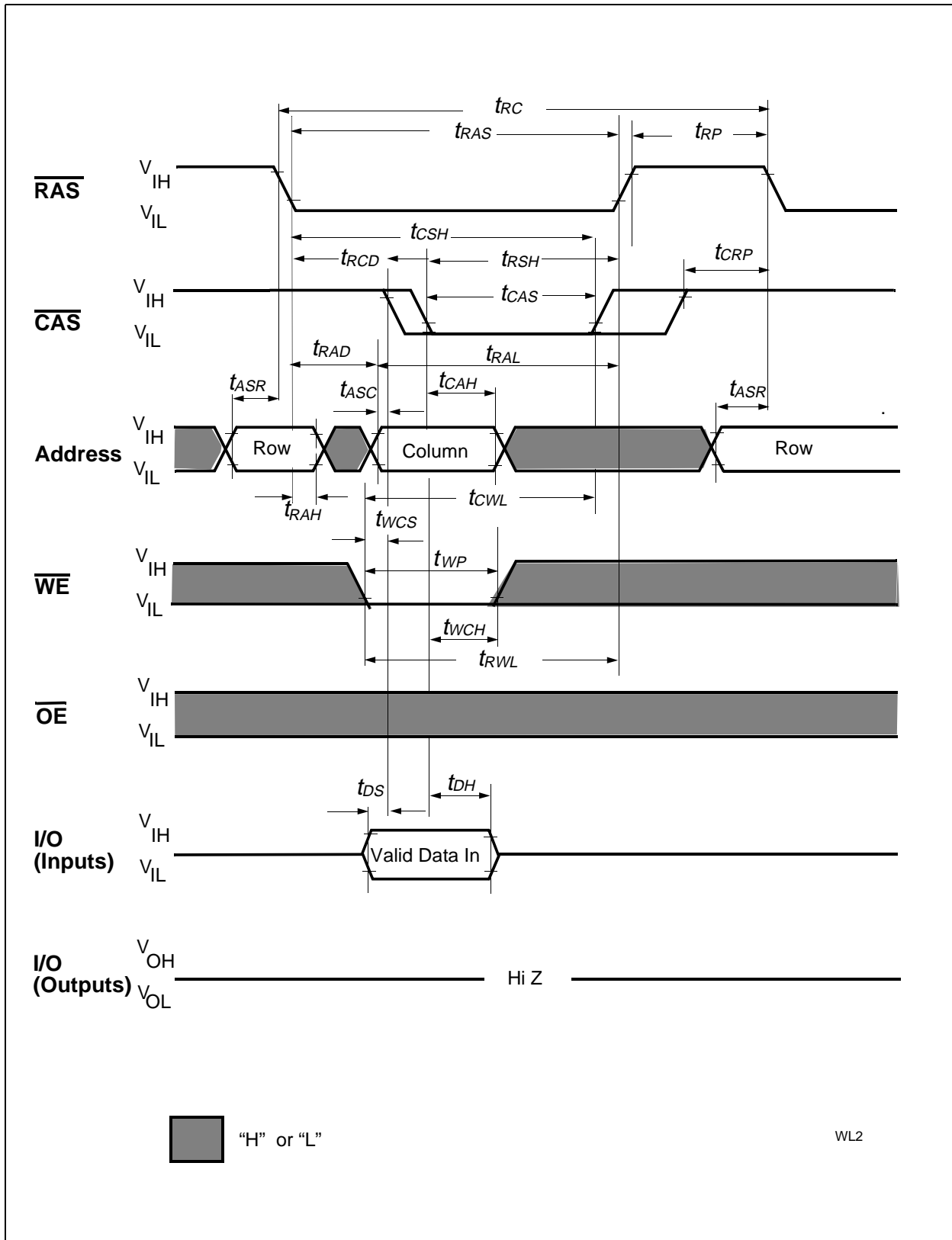
$\overline{\text{RAS}}$ pulse width	t_{RASS}	100k	–	100k	–	100k	–	ns	17
$\overline{\text{RAS}}$ precharge	t_{RPS}	95	–	110	–	130	–	ns	17
$\overline{\text{CAS}}$ hold time	t_{CHS}	-50	–	-50	–	-50	–	ns	17

Test Mode

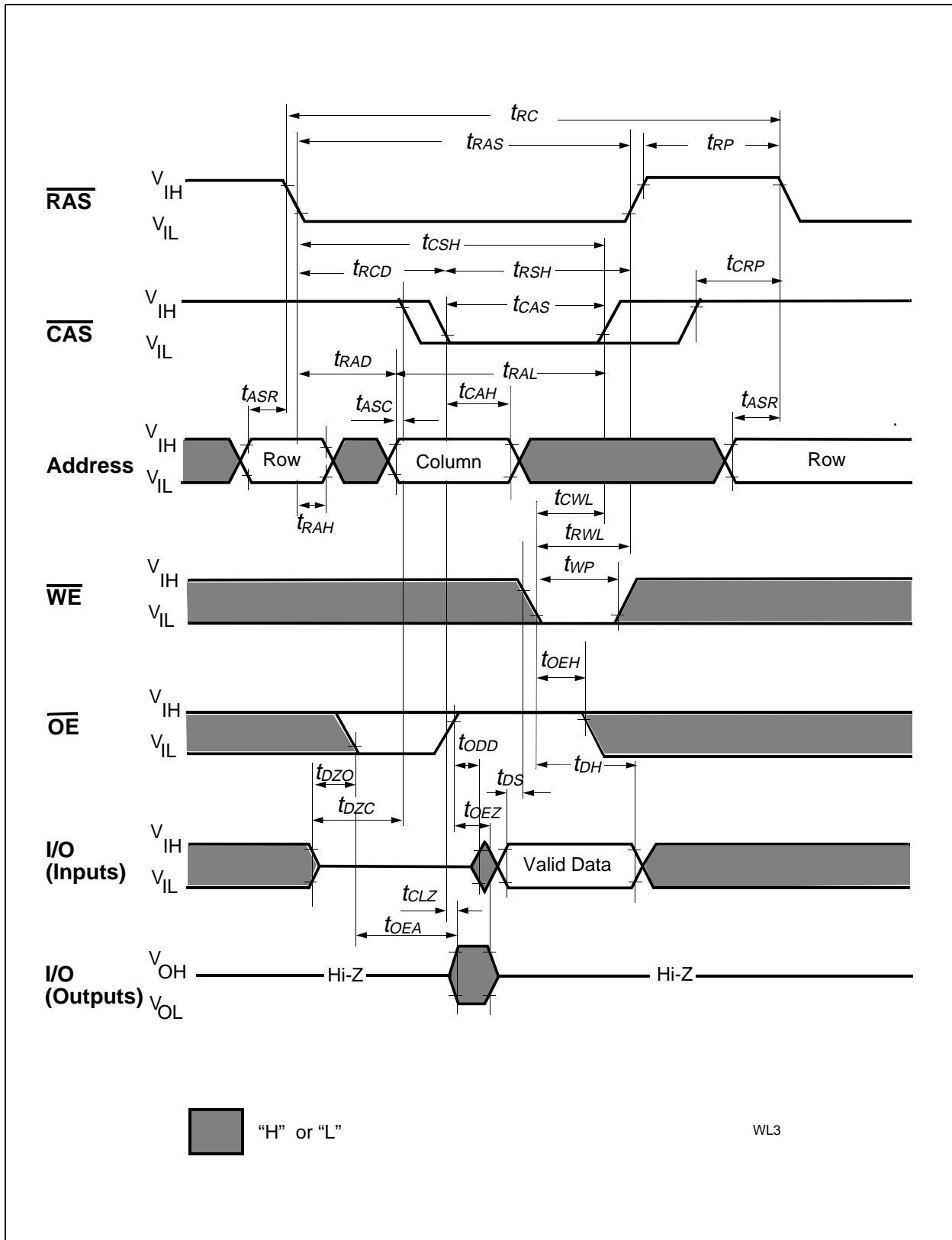
Write command setup time	t_{WTS}	10	–	10	–	10	–	ns	
Write command hold time	t_{WTH}	10	–	10	–	10	–	ns	
$\overline{\text{CAS}}$ hold time	t_{CHRT}	30	–	30	–	30	–	ns	

Notes:

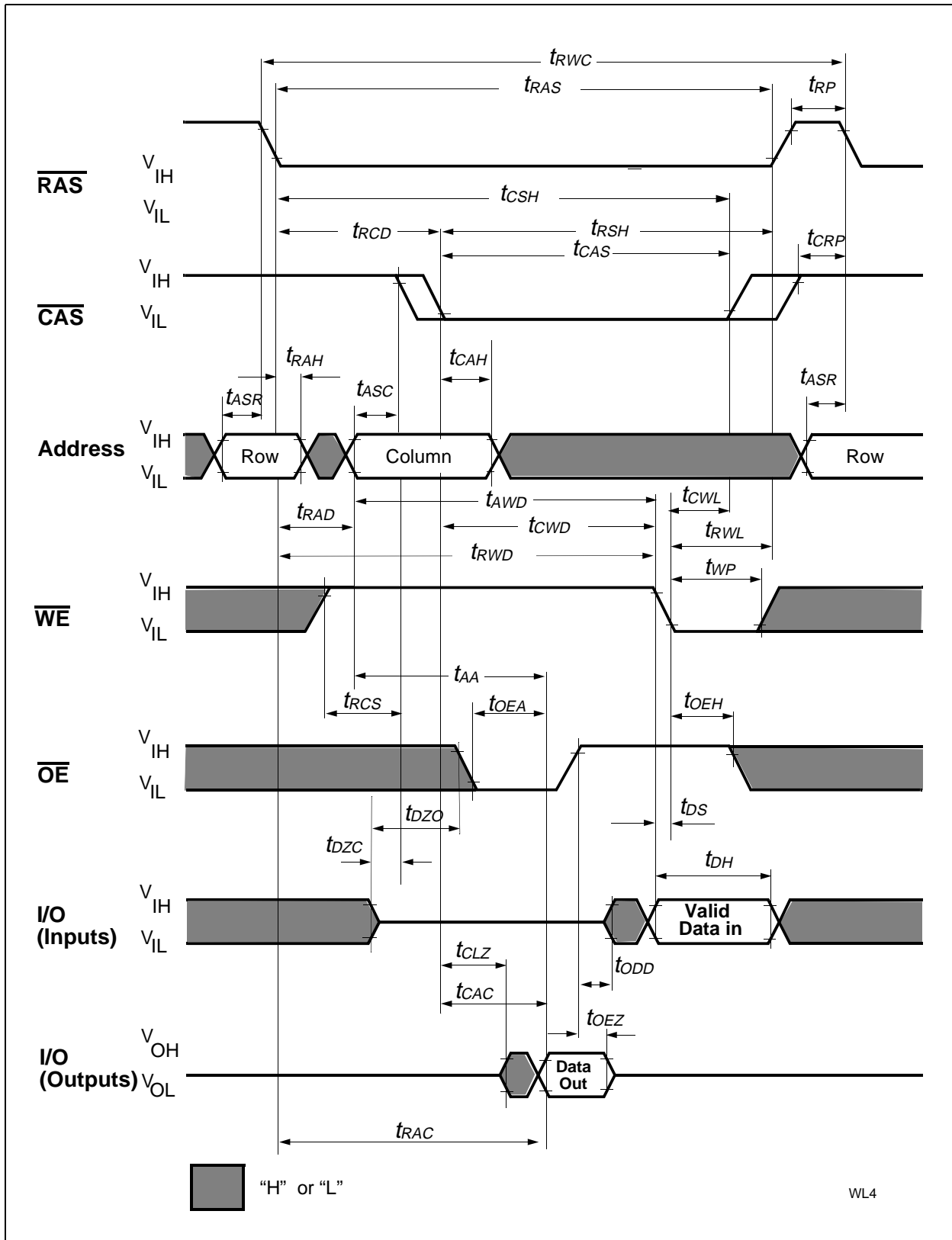
- 1) All voltages are referenced to V_{SS} .
- 2) I_{CC1} , I_{CC3} , I_{CC4} and I_{CC6} depend on cycle rate.
- 3) I_{CC1} and I_{CC4} depend on output loading. Specified values are obtained with the output open.
- 4) Address can be changed once or less while RAS = V_{IL} . In case of ICC4 it can be changed once or less during a hyper page mode (EDO) cycle
- 5) An initial pause of 200 μ s is required after power-up followed by 8 RAS cycles of which at least one cycle has to be a refresh cycle, before proper device operation is achieved. In case of using the internal refresh counter, a minimum of 8 CAS-before-RAS initialization cycles instead of 8 RAS cycles are required.
- 6) AC measurements assume $t_T = 2$ ns.
- 7) $V_{IH (min.)}$ and $V_{IL (max.)}$ are reference levels for measuring timing of input signals. Transition times are also measured between V_{IH} and V_{IL} .
- 8) Measured with the specified current load and 100 pF at $V_{OL} = 0.8$ V and $V_{OH} = 2.0$ V. Access time is determined by the latter of t_{RAC} , t_{CAC} , t_{AA} , t_{CPA} , t_{OEA} . t_{CAC} is measured from tristate.
- 9) Operation within the $t_{RCD (max.)}$ limit ensures that $t_{RAC (max.)}$ can be met. $t_{RCD (max.)}$ is specified as a reference point only. If t_{RCD} is greater than the specified $t_{RCD (max.)}$ limit, then access time is controlled by t_{CAC} .
- 10) Operation within the $t_{RAD (max.)}$ limit ensures that $t_{RAC (max.)}$ can be met. $t_{RAD (max.)}$ is specified as a reference point only. If t_{RAD} is greater than the specified $t_{RAD (max.)}$ limit, then access time is controlled by t_{AA} .
- 11) Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
- 12) $t_{OFF (max.)}$, $t_{OEZ (max.)}$ define the time at which the output achieves the open-circuit conditions and are not referenced to output voltage levels. t_{OFF} is referenced from the rising edge of RAS or CAS, whichever occurs last.
- 13) Either t_{DZC} or t_{DZO} must be satisfied.
- 14) Either t_{CDD} or t_{ODD} must be satisfied.
- 15) t_{WCS} , t_{RWD} , t_{CWD} and t_{AWD} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only. If $t_{WCS} > t_{WCS (min.)}$, the cycle is an early write cycle and data out pin will remain open-circuit (high impedance) through the entire cycle; if $t_{RWD} > t_{RWD (min.)}$, $t_{CWD} > t_{CWD (min.)}$ and $t_{AWD} > t_{AWD (min.)}$, the cycle is a read-write cycle and I/O will contain data read from the selected cells. If neither of the above sets of conditions is satisfied, the condition of I/O (at access time) is indeterminate.
- 16) These parameters are referenced to the \overline{CAS} leading edge in early write cycles and to the \overline{WE} leading edge in read-write cycles.
- 17) When using Self Refresh mode, the following refresh operations must be performed to ensure proper DRAM operation:
 If row addresses are being refreshed on an evenly distributed manner over the refresh interval using CBR refresh cycles, then only one CBR cycle must be performed immediately after exit from Self Refresh.
 If row addresses are being refreshed in any other manner (ROR - Distributed/Burst; or CBR-Burst) over the refresh interval, then a full set of row refreshes must be performed immediately before entry to and immediately after exit from Self Refresh



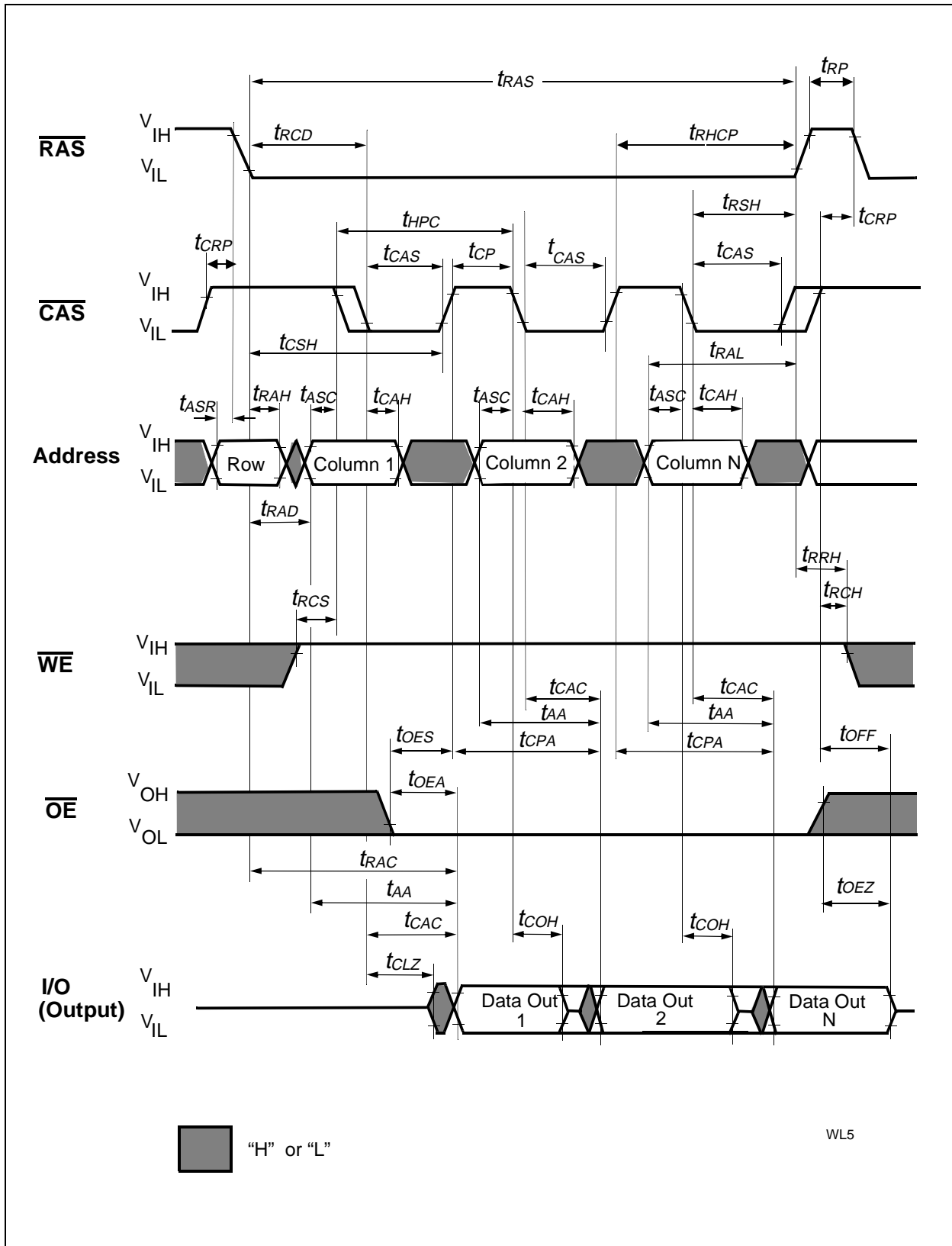
Write Cycle (Early Write)



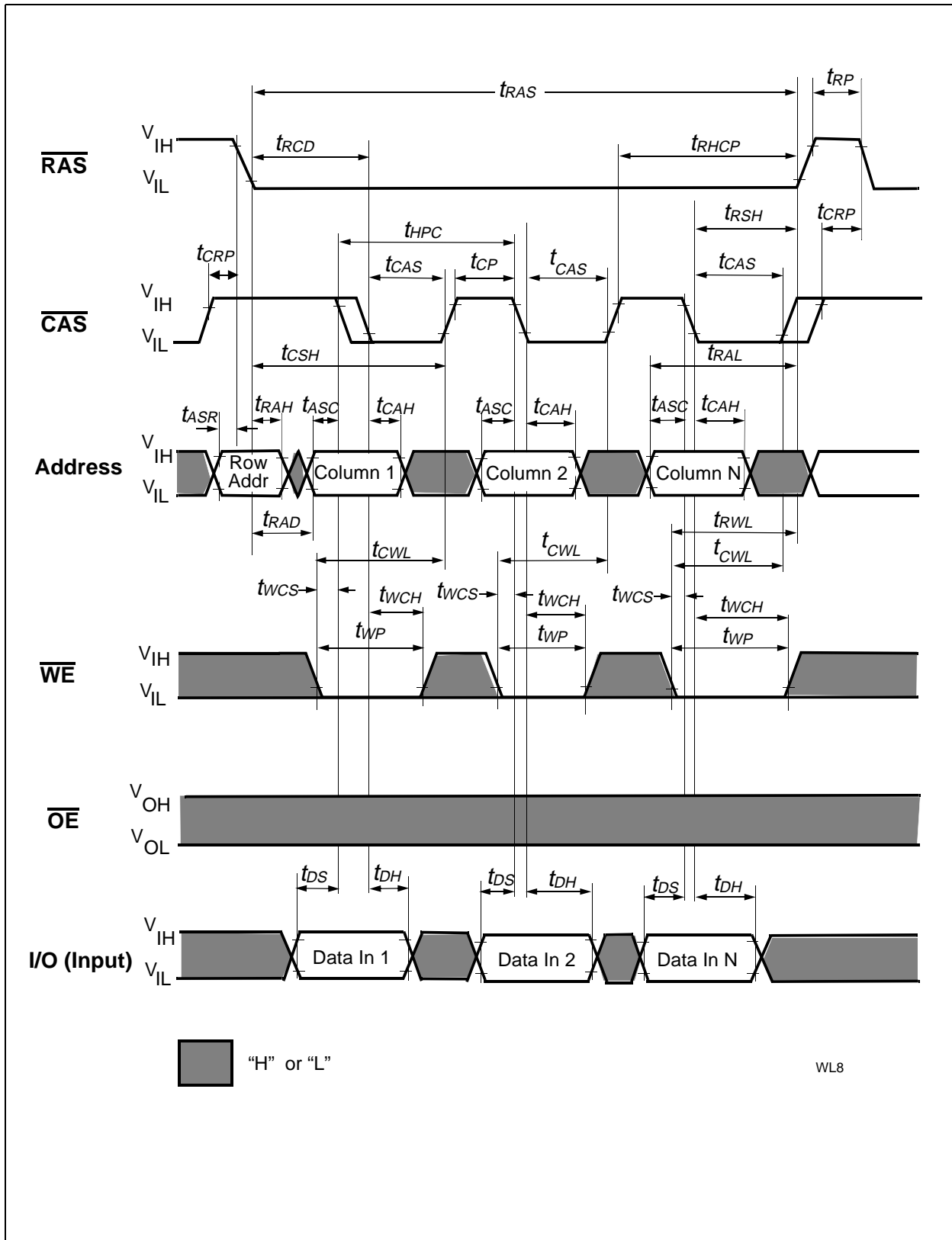
Write Cycle (\overline{OE} Controlled Write)



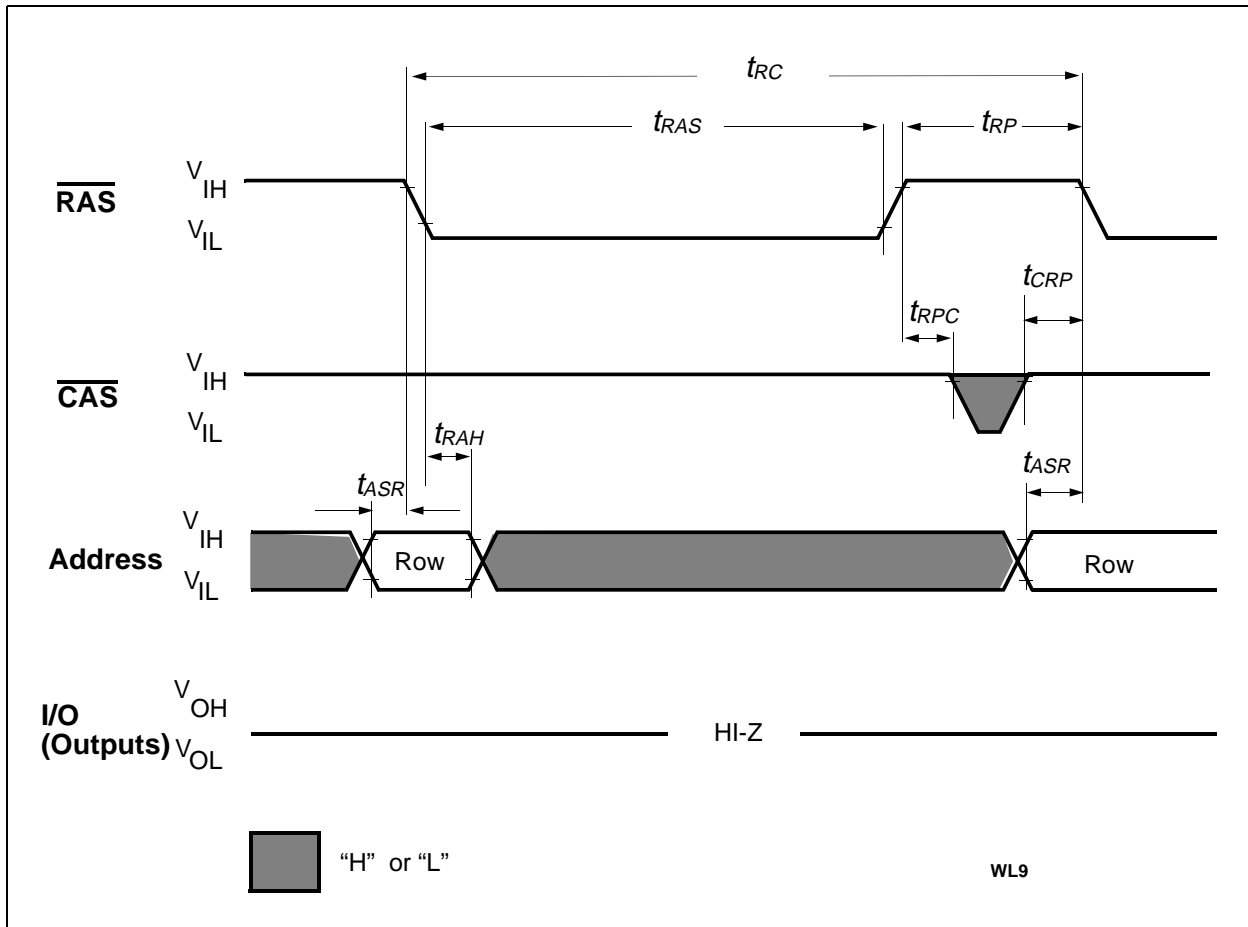
Read-Write (Read-Modify-Write) Cycle



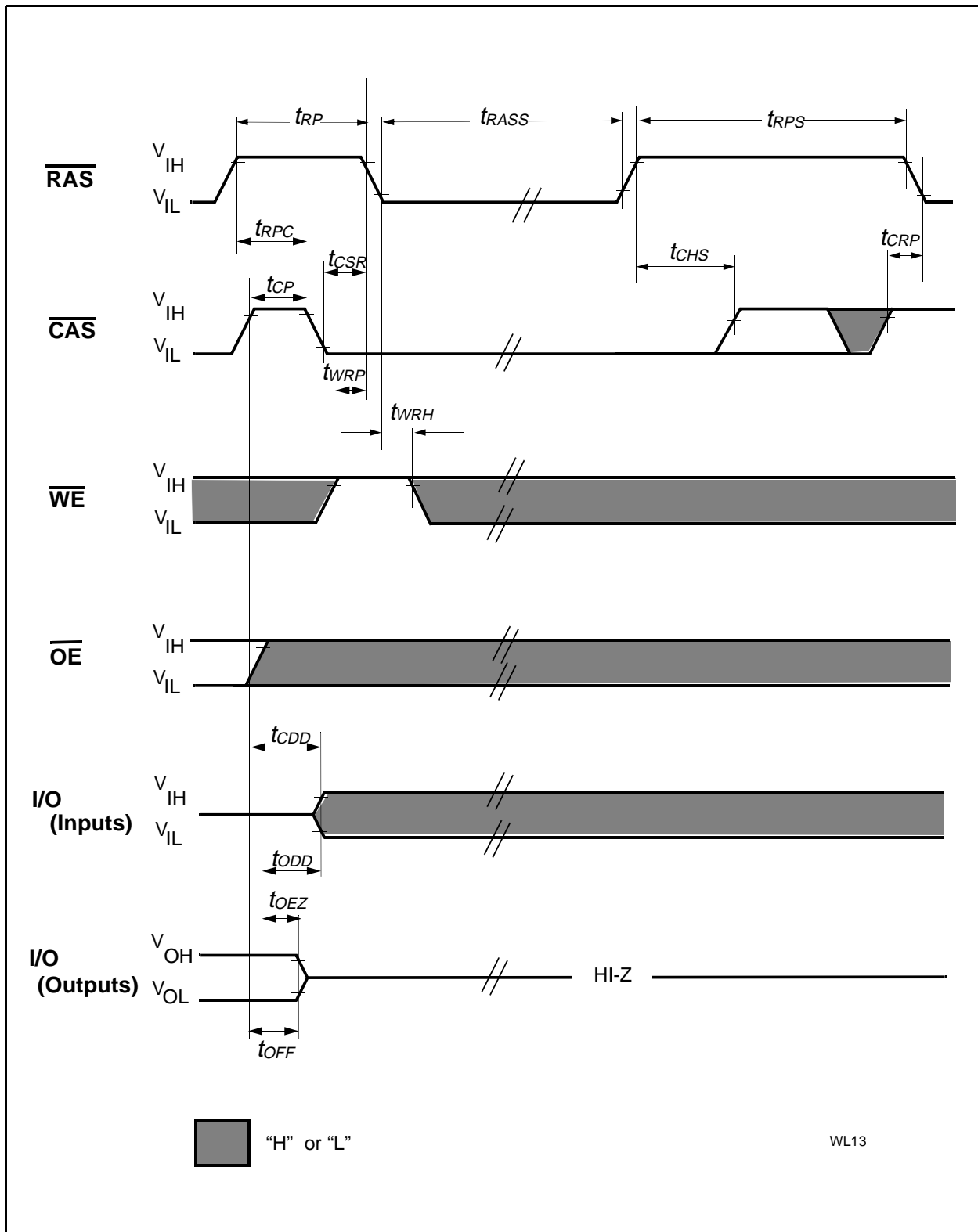
Hyper Page Mode (EDO) Read Cycle



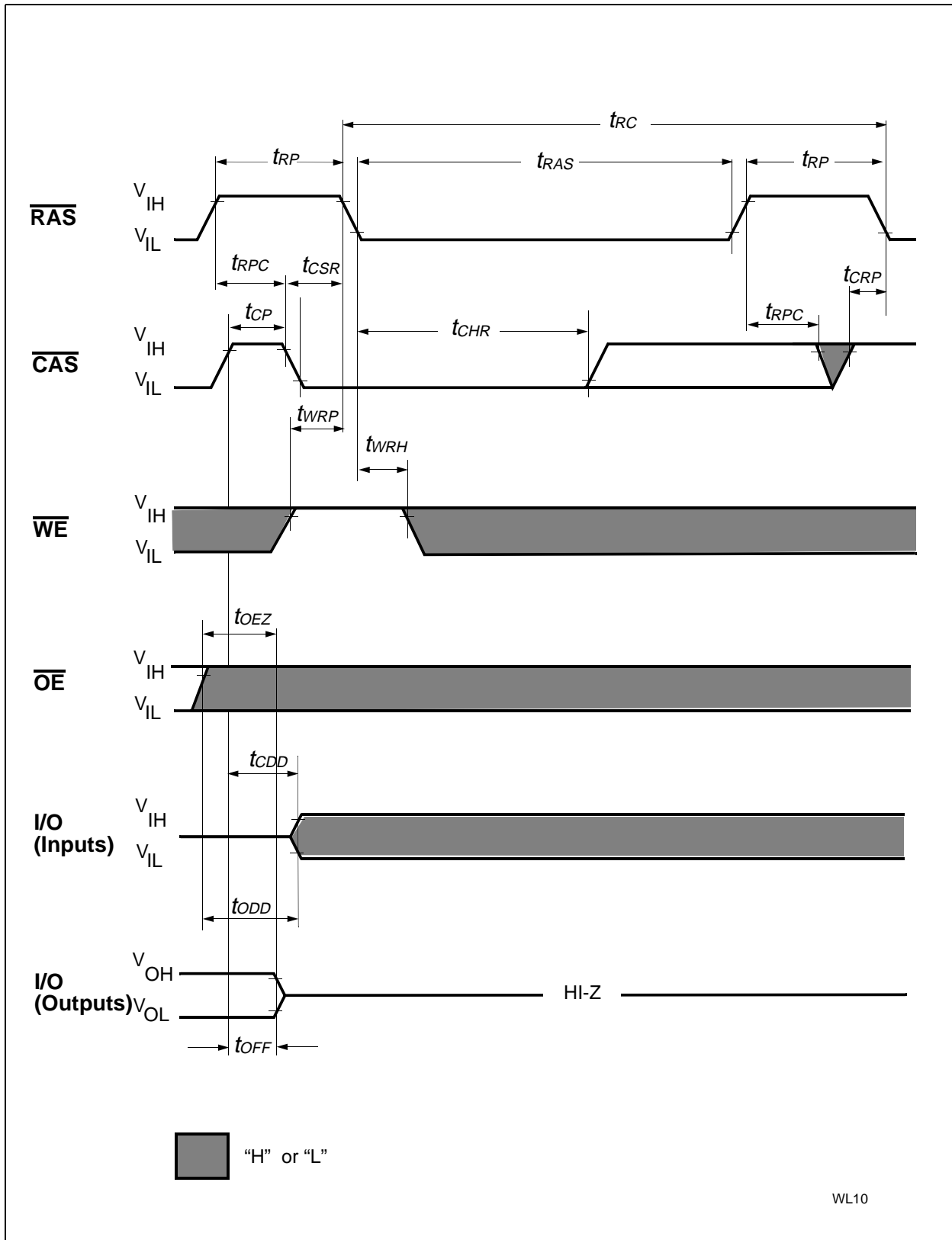
Hyper Page Mode (EDO) Early Write Cycle



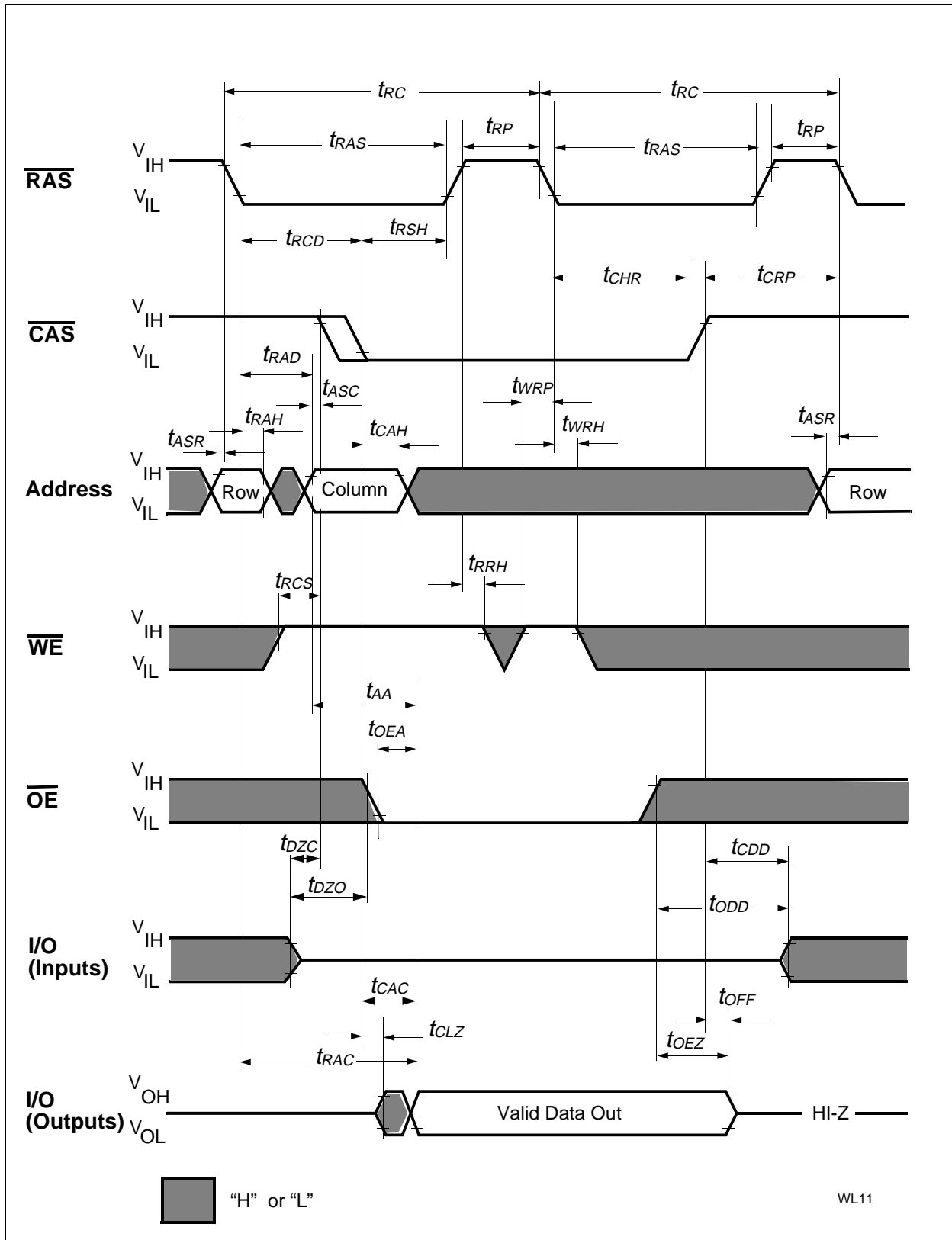
RAS-Only Refresh Cycle



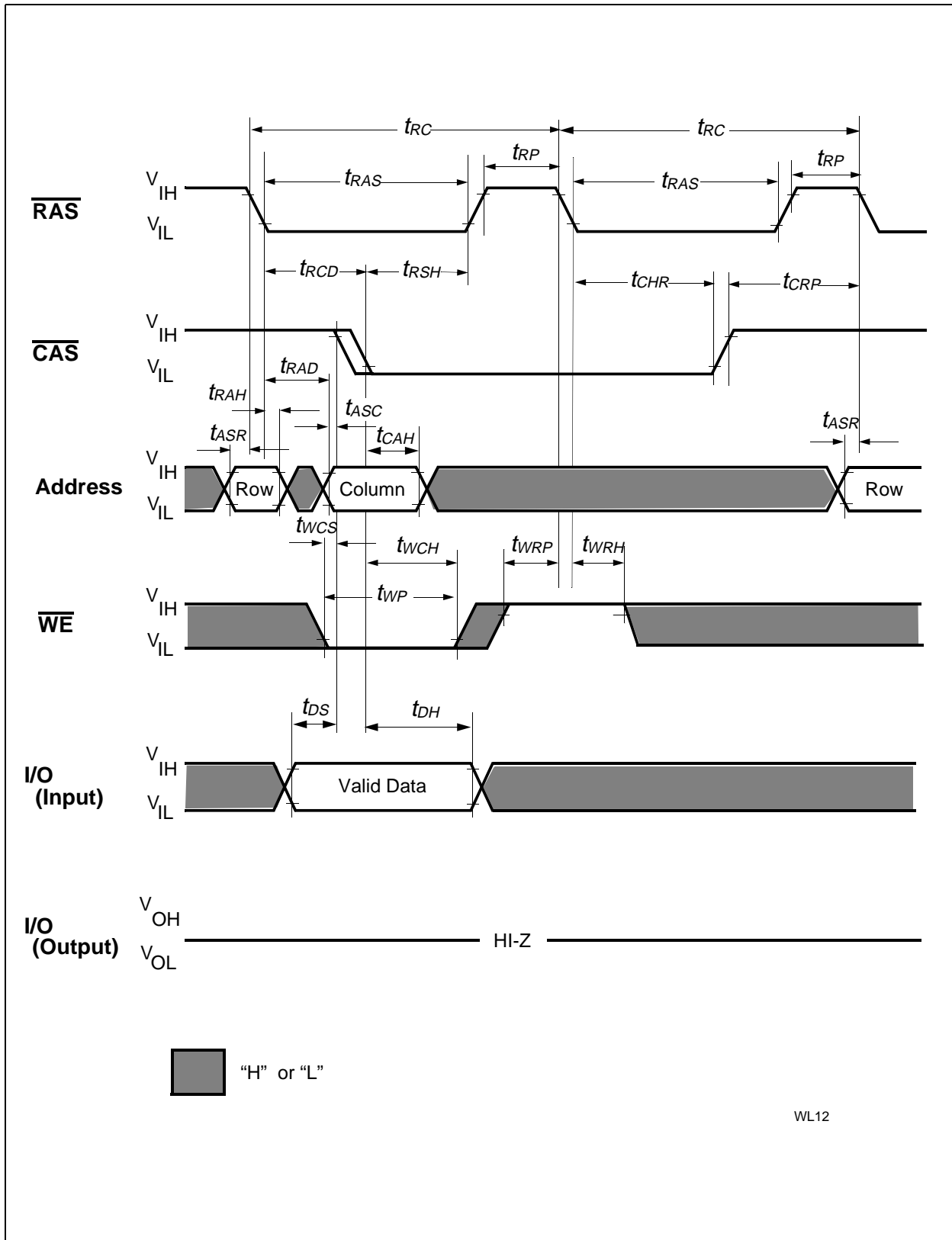
Self Refresh



CAS-Before-RAS Refresh Cycle

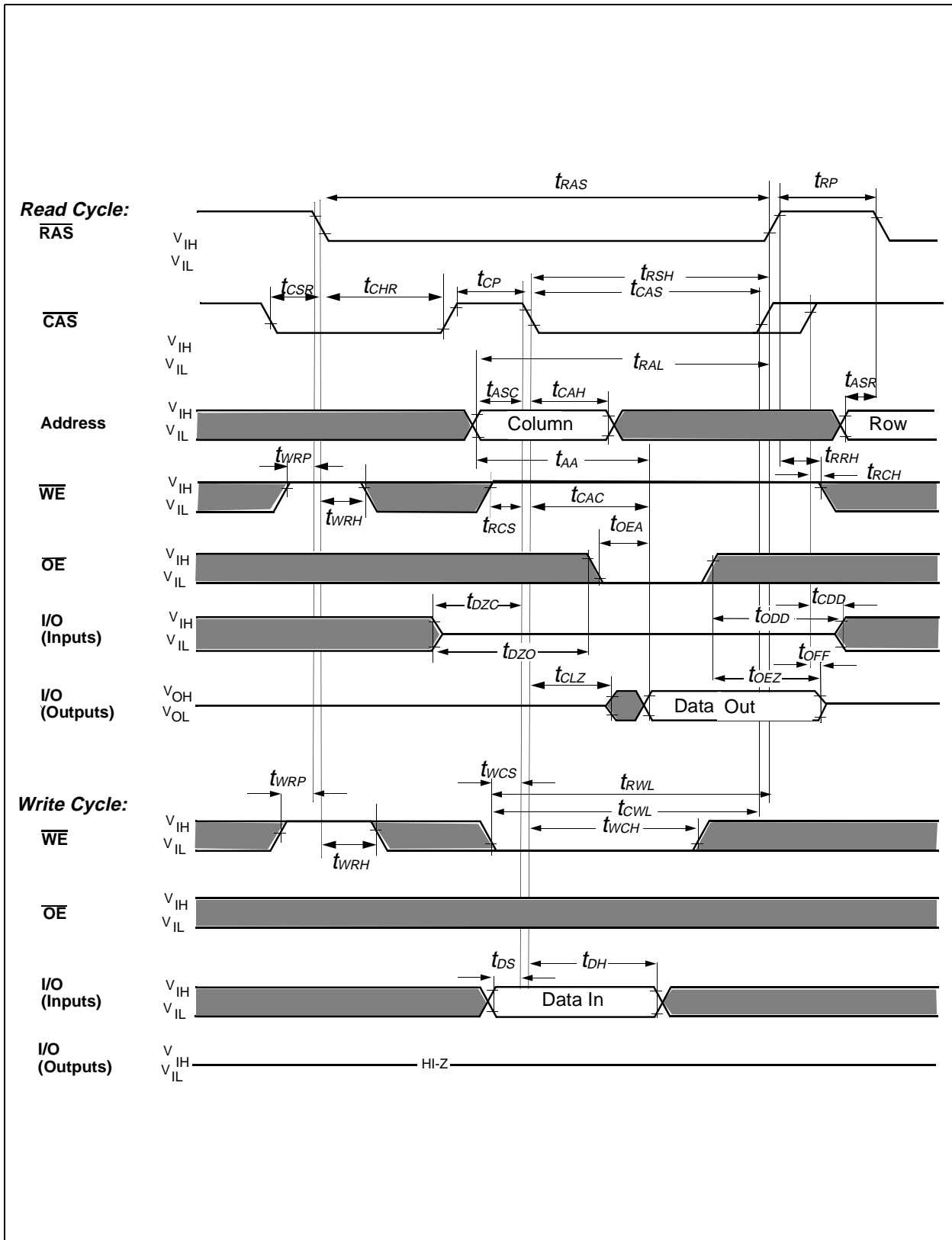


Hidden Refresh Cycle (Read)

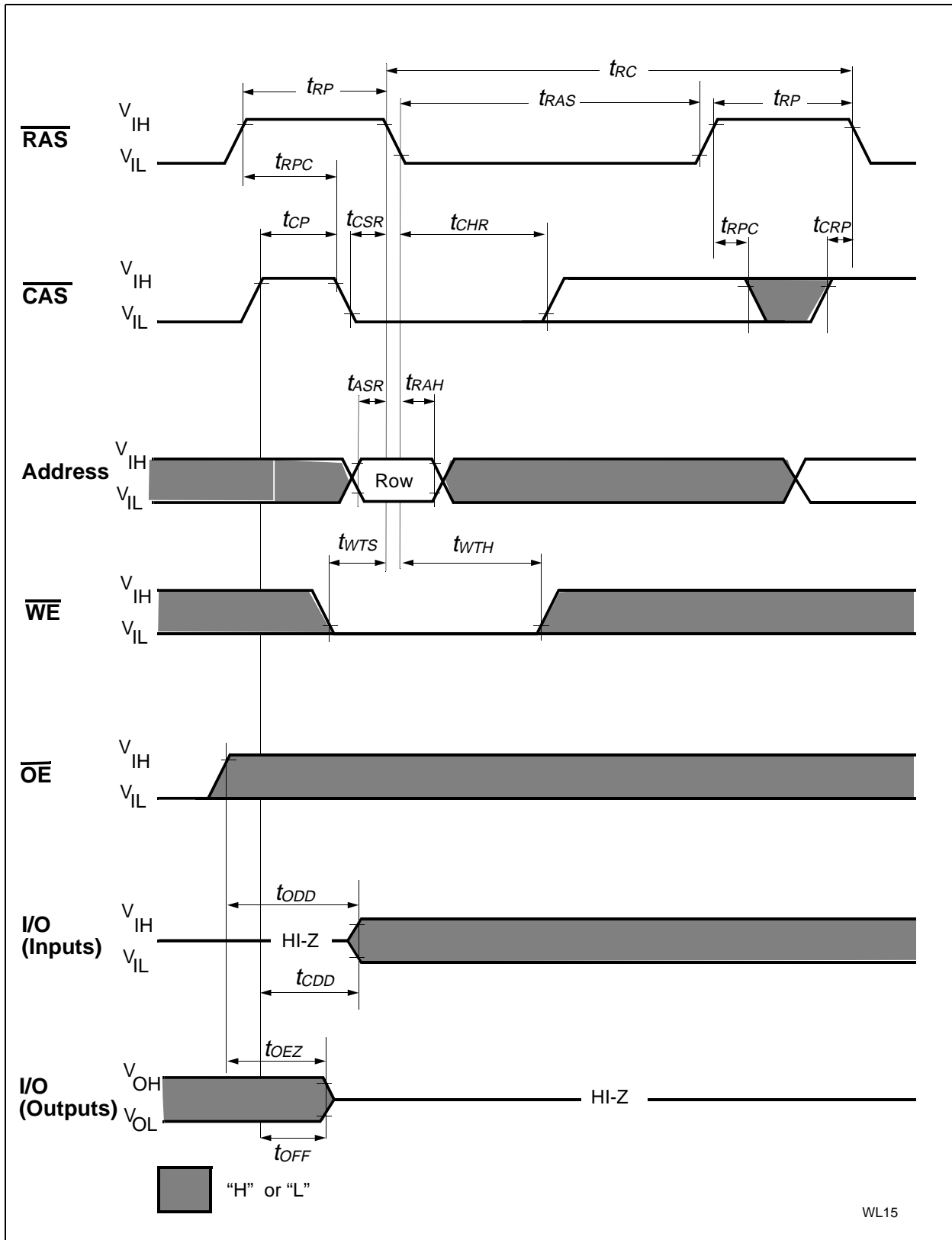


WL12

Hidden Refresh Cycle (Early Write)



CAS-Before-RAS Refresh Counter Test Cycle

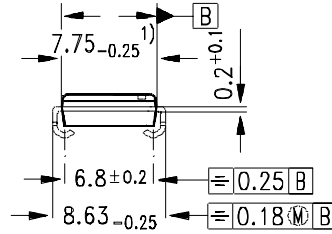
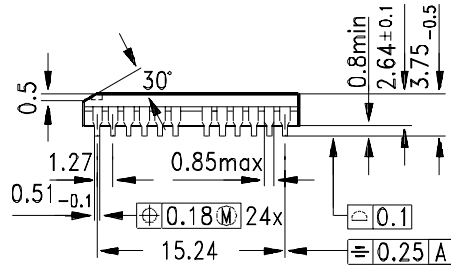


WL15

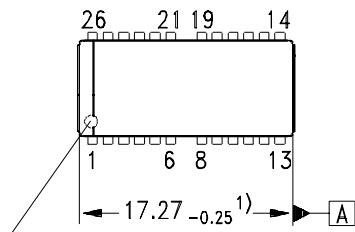
Test Mode Entry

Package Outlines

Plastic Package P-SOJ-26/24-1 (300 mil)
(Small Outline J-leads, SMD)

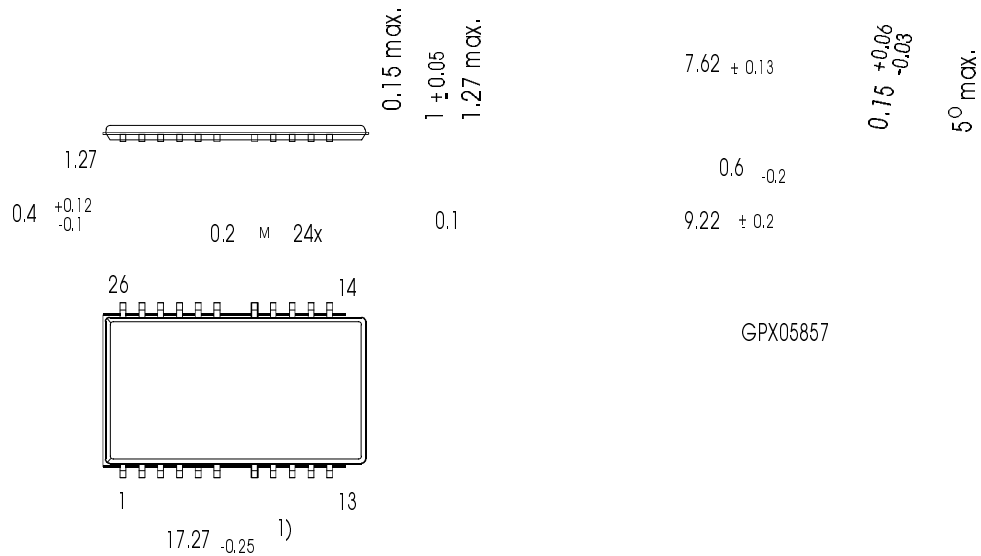


GPJ05628



Index Marking

1) Does not include plastic or metal protrusion of 0.15 max per side



GPX05857

Index Marking